

ABSTRACT

The present invention relates to an epoxy resin composition having excellent low-temperature curability and excellent permeability into a clearance of a narrow portion.

5 An epoxy resin composition containing components (A) to (C) below:

the component (A): a compound having two or more epoxy groups;

the component (B): silica treated with phenylaminosilane;
10 and

the component (C): a compound curing the component (A).

No Figure